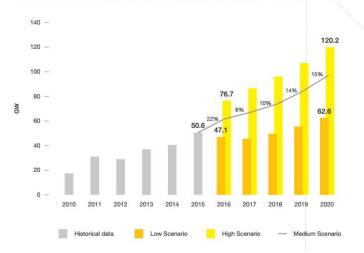
TI 10KW High efficient/small size solar inverter new solution

Texas Instruments April, Y18



WW Solar Trends

FIGURE 8 GLOBAL ANNUAL SOLAR PV MARKET SCENARIOS UNTIL 2020



- · China is expected to install 30+GW in 2017
- 570+GW of Cumulative growth by 2022
- 5%+ growth CAGR 2017-2022

FIGURE: Top 10 Global PV Inverter Vendors by Shipments and Revenue, 2015

Ranking by Total PV Inverter Shipments (MWac)		Ranking by Total PV Inverter Revenue (\$M	
Rank	Company	Rank	Company
1	Huawei	1	SMA
2	Sungrow	2	Huawei
3	SMA	3	Sungrow
4	ABB	4	ABB
5	Sineng	5	SolarEdge
6	TMEIC	6	TMEIC
7	TBEA	7	Enphase
8	Schneider Electric	8	Schneider Electric
9	Power Electronics	9	Omron
10	SolarEdge	10	Tabuchi

Source: GTM Research's Global PV Inverter and MLPE Landscape



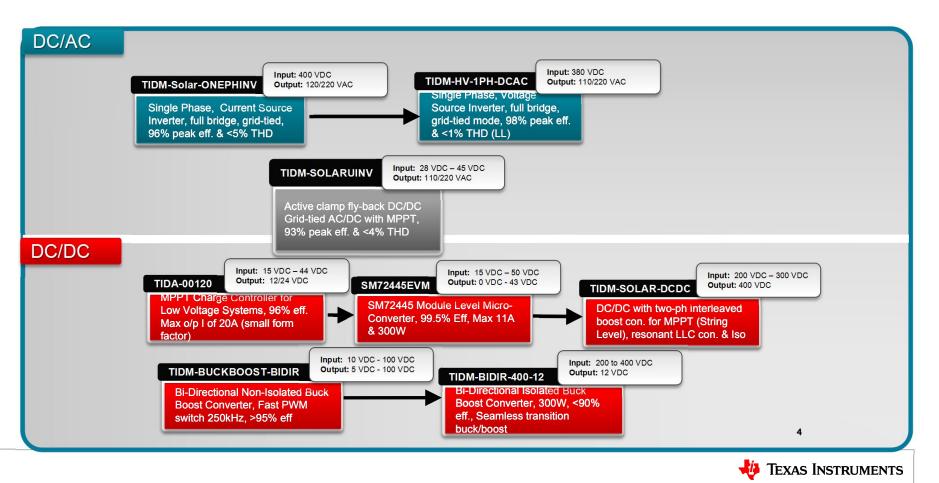
http://www.greentechmedia.com/articles/read/huawei-and-sma-lead-gtm-researchs-2015-global-pv-inverter-rankings http://press.ihs.com/press-release/technology/sma-retains-top-ranking-global-pv-inverter-market-competitors-are-gaining-i



TI Design map for Solar Inverters and Renewable Energy Storage



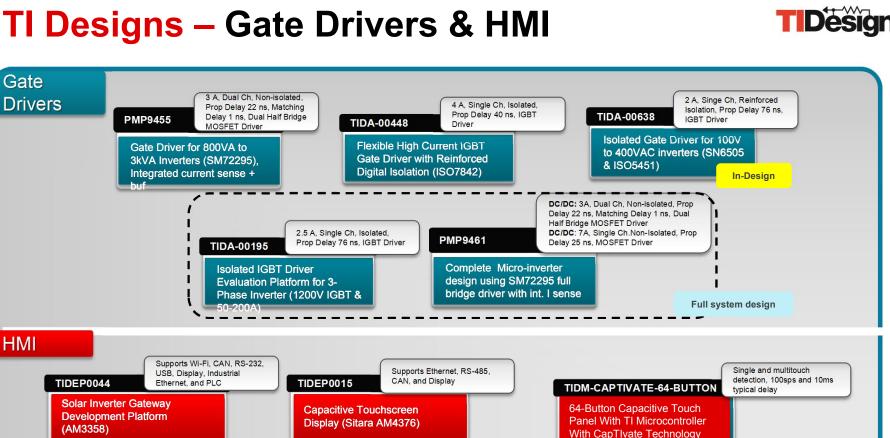
TI Designs – Power Conversion Stages



TI Designs – Gate Drivers & HMI

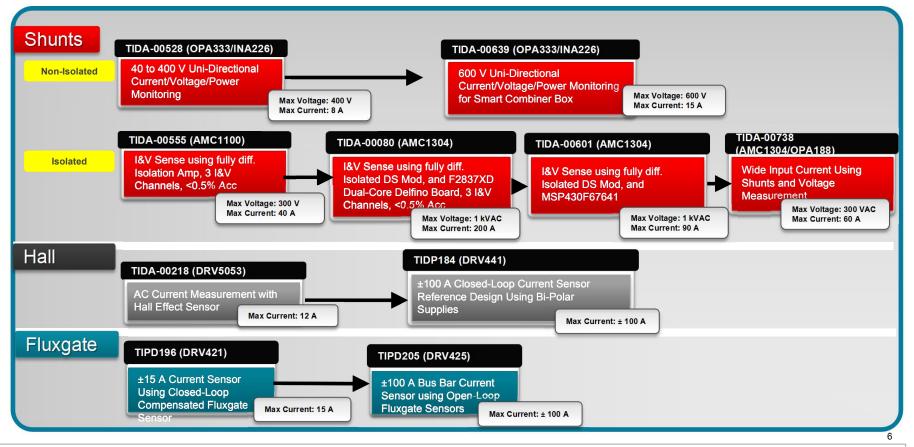
Gate

HMI



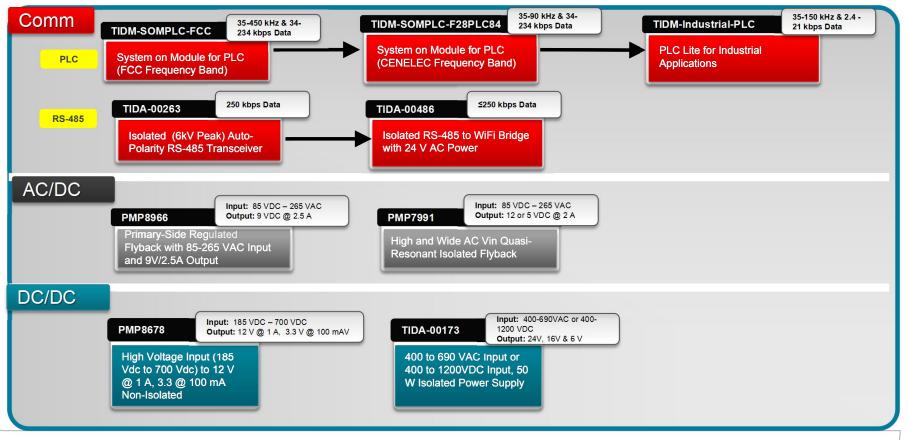


TI Designs – V & I Sensing





TI Designs – Communication & Power Supply





TI 10KW Solar Inverter Design(TIDA-01606)



TIDA-01606

10kW 3-Phase 3-Level Grid Tie inverter reference design for solar string inverter

Design Features

- 10kW 3-Phase 3-Level inverter using SiC MOSFETs
- System Specifications:
 - Input

: 800V/1000V

: 10KW/10KVA

: > 99% peak efficiency

: 400VAC 50/60 Hz

: 50kHz

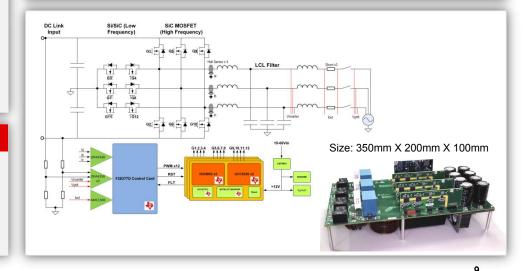
- Output Power
- Efficiency
- PWM frequency
- Uses ISO5852, UCC5320 gate driver & C2000 MCU controller
- Uses Littelfuse LSIC1MO120E0080 1200V 80mOhms SiC MOSFETS
- Reduces output filter size by switching inverter at 50KHz
- Isolated current sensing using AMC1306 for load current monitoring
- Differential voltage sensing using OPA4350 for load voltage monitoring
- Targets less than 2% output current THD at full load

Tools & Resources

- TIDA-01606 Tools Folder
- Test Data/Design Guide
- Design Files: Schematics, BOM and BOM Analysis, Design Files
- Key TI Devices: UCC5320, ISO5852, AMC1306, SN6505, TMS320F28379D, OPA4350, OPA350, LM76003, PTH08080WAZT, UCC27211

Design Benefits

- 3-Level T-type inverter topology for reduced ground current in transformer-less grid-tie inverter applications
- Reduced size at higher efficiency using low Rdson SiC MosFET and higher switching frequency (50kHz) at higher power (10kW)
- Platform for testing both 2-level and 3-level inverter by enabling or disabling middle devices through digital control.





Specifications

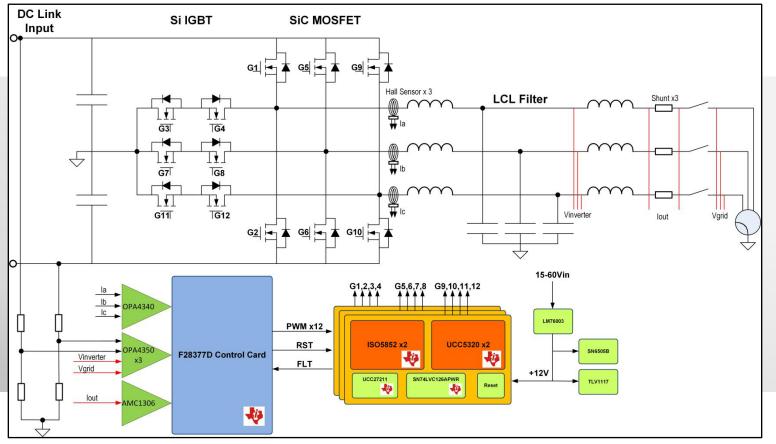
AC Output	Power (KW/KVA)	10/10	
	PF rated/adjustable	1/0.7lag to 0.7lead	
	Grid Voltage (L-L)	400V ± 20%	
	No of Phases	3	
	Frequency	50/60Hz ± 5Hz	
	Current (Max)(A)	18	
DC Input	Nominal Voltage (V)	800	
	Rated Min/Max Voltage (V)	600/1000	
Performance	Efficiency (peak/European)	98.5%	
	Output current THD	<2%	
Other Specs	Off Grid operation	No	
	Operating temperature	-25°C to +60°C	
	Thermal management	Forced air cooling	

Target End Equipment's

String Inverters – Residential/Commercial



Topology & System Architecture





10kW Three Level Inverter Hardware

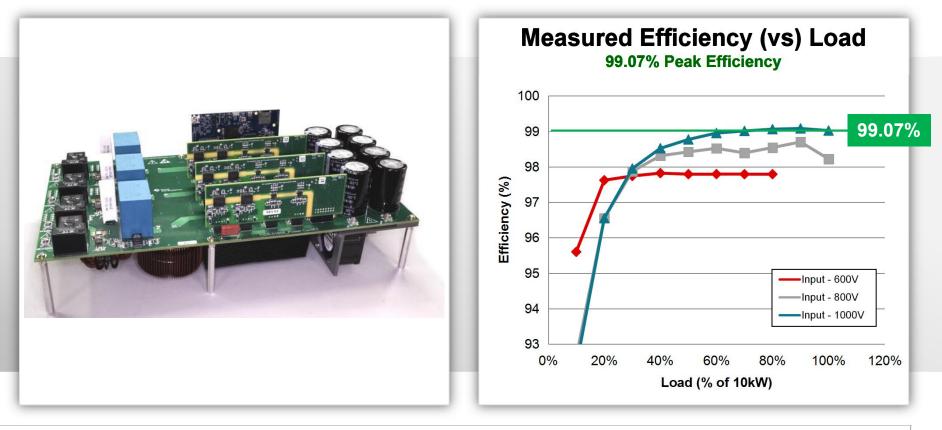




Total Size: 350mmx 200mm x 100mm



10kW Three Level Inverter Measurements





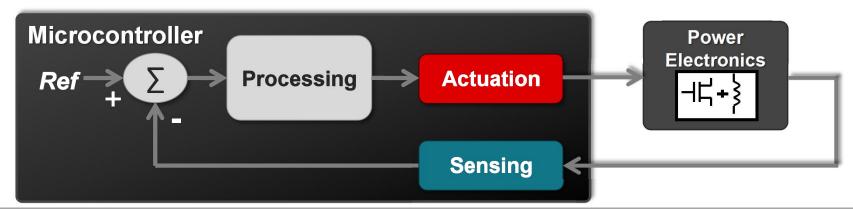
10kW Three Level Inverter Summary

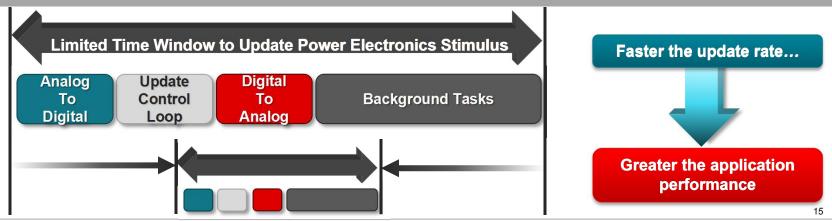
- 99.07% Peak Efficiency at 8kW
- 99.02% Efficiency at 10kW
- 1.4kW/l

Measured Results Summary				
SYSTEM PARAMETER	VALUE			
Input Voltage	600-1000Vdc			
Output Voltage	400VAC 50/60Hz			
Maximum Power	10kW			
PWM Frequency	50kHz			
Efficiency (Peak)	99.07% @ 8kW			
Efficiency (Full Load)	99.02% @ 10kW			
Size	350mm x 200mm x 100mm			



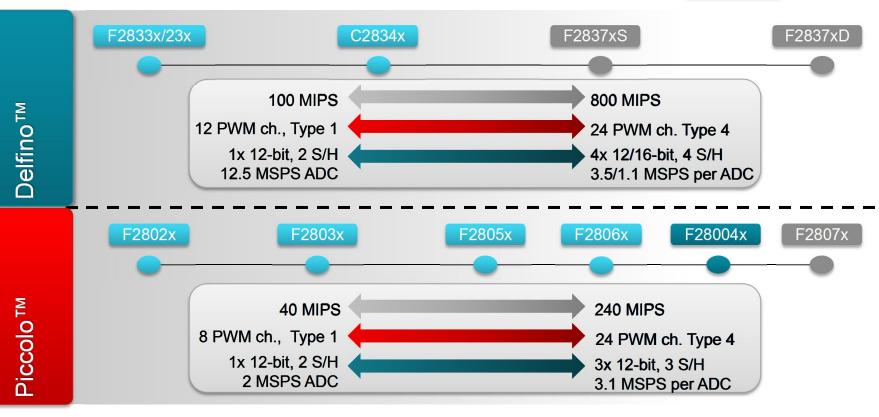
C2000 - Essentials of Real-time Control







C2000 - The Real-Time Control Portfolio





Production

Sampling

Delfino[™] TMS320F2837xD

Features

- 800MIPS real-time performance of dual C28x core with dual CLA co-processors to run parallel control loops
- 4 differential 16-bit ADC, 1MSPS each and 3x 12-bit DAC
- Trigonometric Math Unit (TMU) 1 to 3 cycle SIN, COS, ARCTAN instructions
- Direct memory access through dual EMIFs (16bit/32bit)
- Protection with 8x Windowed Comparators and X-Bar
- 8 Sigma Delta Decimation Filters to enable sensing across the isolation boundary

Tools



TMS320F28379D Experimenter's Kit

Part Number: TMDXDOCK28379D



TMS320F2837xD Temperatures 105C 125C Q100					
Sensing	Processing	Processing		Actuation	
ADC1: 16-bit, 1.1-MSPS 12-bit, 3.5 MSPS	C28x™ DSP core	C28x™ DSP core	12x ePWM Modules (Type 4) 24x Outputs (16x High-Res)		
ADC2: 16-bit, 1.1-MSPS 12-bit, 3.5 MSPS	200 MHz	200 MHz	Fault Trip Zones		
ADC3: 16-bit. 1.1-MSPS	FPU	FPU	3x 12-bit DAC		
12-bit, 3.5 MSPS	TMU	TMU		Connectivity	
ADC4: 16-bit, 1.1-MSPS 12-bit, 3.5 MSPS	VCU-II	VCU-II	4x UART		
8x Windowed Comparators w/ Integrated 12-bit DAC	CLA DSP core	core core 200 MHz 200 MHz	2x I2C (w/ true PMBus) 3x SPI		PMBus)
8x Sigma Delta Interface			2x McBSP		Р
Temperature Sensor	Floating-Point Math	Floating-Point Math	2x CAN 2.0		
3x eQEP	6ch DMA	6ch DMA	US	AAC & PHY	
6x eCAP	Memory	Memory	uPP		
System Modules	System Modules Up to 512 KB		Power & Clocking		ocking
3x 32-bit CPU Timers	Flash	Flash		2x 10 MHz	osc
NMI Watchdog Timer	Up to 102 KB SRAM	Up to 102 KB SRAM	Ext OSC Input		nput
2x 192 Interrupt PIE	2x 128-bit Security Zones		Debug		3
	Boot ROM			Real-time J	TAG
	2x EMIF				

Packages	
Package	Dimension
176-pin HLQFP	24x24mm ²
337-pin NFBGA	16x16mm ²



UCC53xx Family

0.5/2/4/6A/10A Isolated IGBT/SiC Gate Drivers with High CMTI

Features

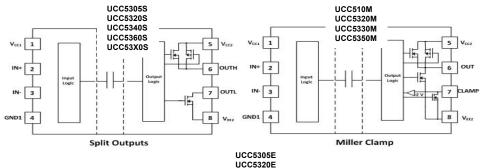
- Integrated SiO₂ Dielectric Capacitor
 - 0.5A, 2A, 4A, 6A, 10A Peak Source/Sink Drive
 - Flexibility and Options
 - Split Outputs (ISO53xxS)
 - UVLO with respect to IGBT emitter (ISO53xxE)
 - Miller Clamp option (ISO53xxM)
 - 100 kV/us CMTI min
 - 70 ns (max) Prop Delay.
 - 4kV ESD on all pins
- Immunity and Certifications
 - Basic and Reinforced Isolation Options
 - Upto 5.0 kVrms Isolation rating (UL 1577)
 - Upto 8kVpk Transient (VDE0884-10)
 - Upto 1414 Vpk Working Voltage (VDE0884-10)
 - Enables IEC61800-5-1, IEC60664-1 & IEC62109-1
- Power and Package
 - Wide V_{CC2} Range: 15V-35V
 - 8-pin Narrow Body SOIC (4 mm Creepage)
 - 8-pin Wide SOIC Package (>8.3mm Creepage)
 - 3V to 15V input supply range.
 - Extended Temp: -55 to 125 °C

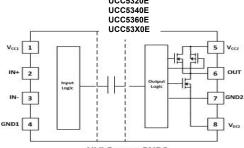
Applications

- Industrial Motor Control Drives
- Industrial Power Supplies
- Solar Inverters
- HEV & EV power modules

Benefits

- · Reinforced isolation rating
- Different configuration options available
- Improved system performance
- Enabling low power & efficient solutions





UVLO w.r.t GND2



ISO5852S: +2.5A/-5A, Isolated, High CMTI, Miller Clamp

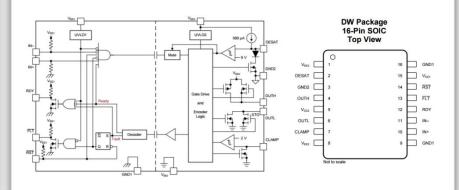
Features

- Integrated SiO₂ Dielectric Capacitor
 - CMOS compatible logic input threshold
 - Safety Features: Miller Clamp, Desat Detect, UVLO, Fault feedback, Ready status feedback, auto soft-shutdown on short
 - +2.5/-5A Peak Source/Sink Split Outputs
 - 120 kV/µs CMTI (typ) / 100 kV/µs (min)
 - 30ns Integrated Glitch Filter
 - 110 ns (max) Prop Delay
 - 4kV ESD on all pins
- Immunity and Certifications
 - 12.8 kVpk Surge (8 kV V_{IOSM}) per VDE Reinforced Isolation
 - 5.7 kVrms Isolation rating per UL1577
 - 8000 Vpk V_{IOTM} (transient) and 2121 Vpk V_{IORM} (working voltage) per VDE0884-10
 - Enables IEC61800-5-1, IEC60664-1 & IEC62109-1
- Power and Package
 - Wide V_{CC2} Range: 15V-30V
 - 16-pin Wide SOIC Package (>8mm Creepage)
 - Extended Temp: -40 to 125 °C

Benefits

- Component-level Reinforced rating
- Improved system performance
- Enabling low power & efficient solutions
- High Immunity for Noisy Environments
- High Reliability in Harsh Environments
- Certified by all 3 World Wide agencies

PART #	Split outputs	Soft Turnoff	UVLO+/ UVLO- (typ)	PKG
ISO5852S	Yes	Yes	11.6/10.3	16DW





🚘 : AEC-Q100

AMC1306

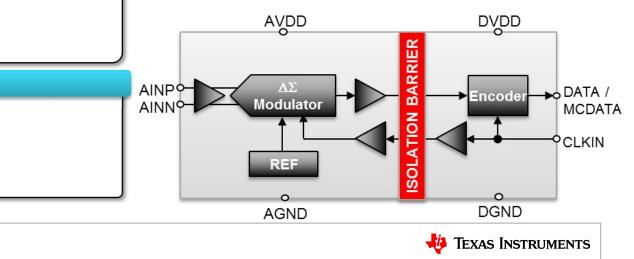
Small Reinforced Isolated Modulator, ±50mV | ±250mV Input, CMOS Interface/Manchester Encoding

Features

- Reinforced Isolation (UL1577 & VDE 0884-10)
 - Working Voltage: 1.5 kV_{RMS}, 2.1 kV_{DC}
 - Isolation Voltage: 7 kV_{PEAK} / 12.8 kV_{SURGE}
 - Isolation Lifetime: >> 135 years
- CMTI: 100 kV/µs (typ) / 50 kV/µs (min)
- Clock: 5-21 MHz (external)
- Various Input Voltage Ranges:
 - ±50 mV & ±250 mV
- Superior DC Performance:
 - Offset / Offset Drift: ±4.5 μV (±100 μV max) / ±1 μV/°C
 - Gain / Gain Drift: ±0.2% (max)/40 ppm/°C (max)
- Manchester-coded Modulator Bitstream Options
- Temperature Range: -40°C to 125°C
- Small Package: SO-8 (DWV)

Benefits

- Unique ±50-mV input & Manchester coded (DC-free) output options
- Reduced input voltage range for lowest P_D on shunt
- Smallest package size
- Simplified clock routing & duty cycle correction with Manchester Encoding
- Missing high-side supply & input common-mode over-range indication

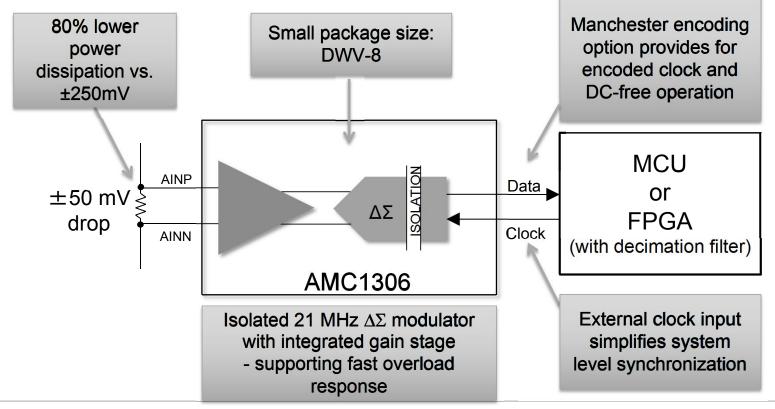


Applications

- Shunt-based Current Measurement:
 - Compact Motor Drives
 - Frequency Inverter Applications
 - Solar Inverters

AMC1306– Advantages

Small Reinforced Isolated Modulator, ±50mV | ±250mV Input, CMOS Interface/Manchester Encoding





Thanks!



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